Optical Module Packaging Inspection

SAKI develops state-of-the-art automated optical and X-ray inspection systems for advanced semiconductor packaging processes. Our solutions accurately detect defects in microbumps, TSVs, ...

Combining our extensive knowledge in automatic optical inspection and optical microscopy we design and manufacture custom solutions for in-line and off-line inspection and metrology.

At InspecVision, we provide cutting-edge metrology systems that empower packaging companies to achieve unrivalled inspection accuracy, reduce waste, and drive profitability.

Optical systems detect whether sealing seams are closed correctly, whether packaging is free of creases or inclusions and whether labels have been applied correctly. Defective packaging can ...

ccurate, micron-level 3D inspection. A laser displacement sensor placed above open boxes uses 3D measurements to ensure that the cap on every ottle inside is properly positioned. Mis-assembled ...

Microscopes for IC package inspection in semiconductor packaging and quality control. Designed for inspecting wire bonding, solder balls, package surfaces, and structural defects using ...

Chip placement on the board is monitored by automated optical inspection (AOI) systems. Individual chips and components are then soldered together with a ball grid array or other advanced techniques ...

Our wafer inspection and metrology systems, augmented by artificial intelligence (Al), allow engineers to quickly detect, resolve and monitor excursions to provide greater control of quality for improved ...

As semiconductor devices continue advancing into more sophisticated packaging schemes, traditional optical inspection technologies are brushing up against physical and ...

Advance optical modules are using mSAP (modified Semi Additive Package) to save cost and power - mSAP was developed in the last 7-10 years in support of smart phones and watches.

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